

Since 1979...

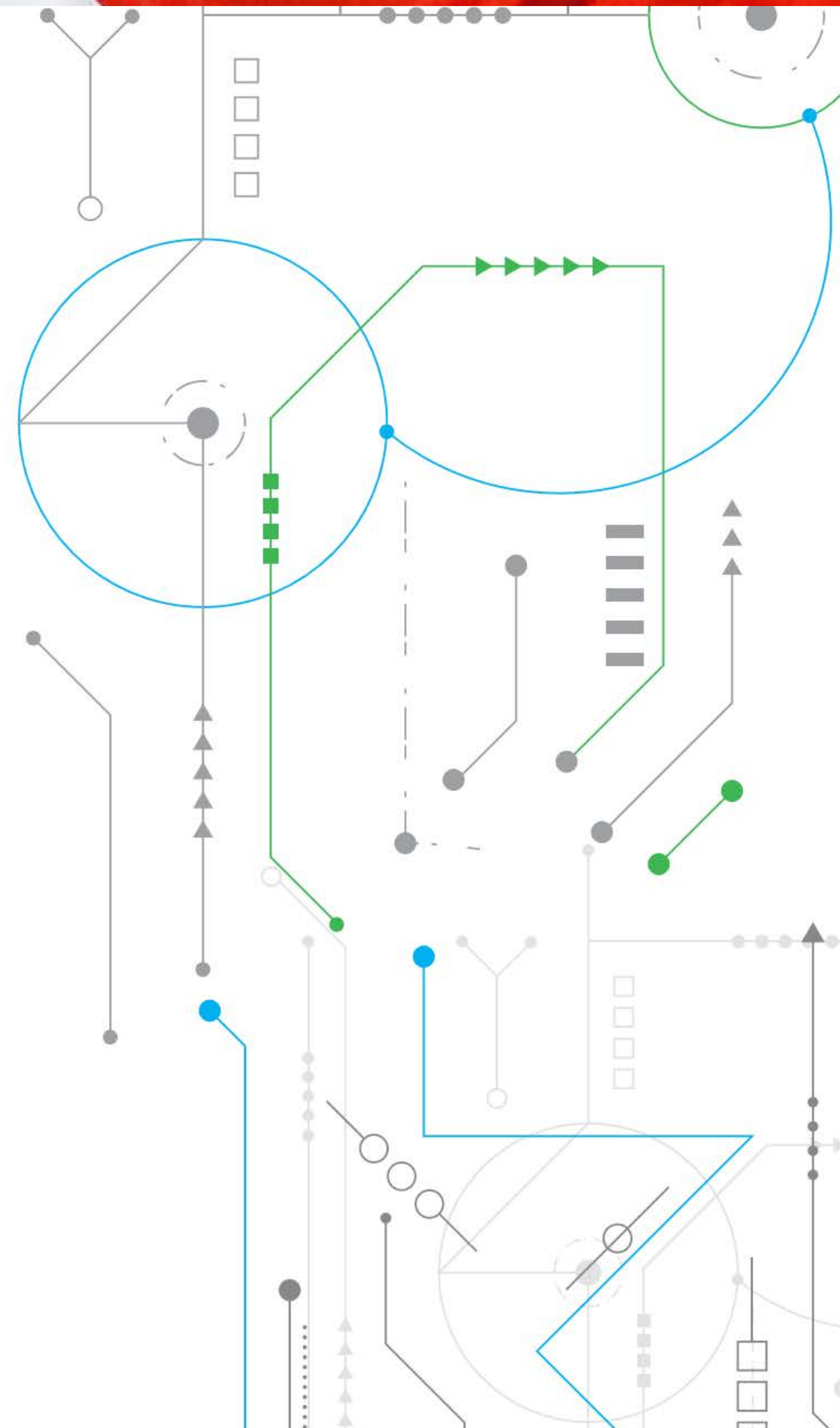
YOUR BEST EUROPEAN PCB PARTNER

"Talent wins games, but teamwork and intelligence wins championships."

Cit. Michael Jordan



esseti 
PRINTED CIRCUIT BOARD



HISTORY:

1979_FOUNDED IN BOLOGNA
1982_BILAYERS PRODUCTION
1993_MULTILAYERS PRODUCTION
1998_UL/UR CERTIFICATION
2000_ISO9001 CERTIFICATION
2002_FAR EAST GUARANTEED IMPORT SERVICE
2008_PRODUCTION CAPABILITY IMPROVED
2020_ISO14000 CERTIFICATION
2021_IMPROVING ITALIAN PRODUCTION LINE
2022_AS9100 FOR AVIONICS APPLICATION
2022_AUTOMATIC VERTICAL LIFT MODULE



AND NOW.. LET'S WRITE THE FUTURE TOGETHER!

MARKET SECTORS:



10%
CONSUMER

60%
RAILWAY
DEFENCE
BROADCAST
MEDICAL

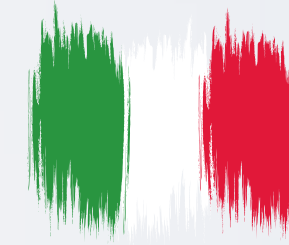
30%
POWER
INDUSTRIAL
LED LIGHTING



ESSETI HQ:



ITALIAN PRODUCTION PLANT



Services

FAST PROTOTYPE PRODUCTION SERVICE-24H/72H

FAST MASS PRODUCTION SERVICE - 3/8 W-DAYS

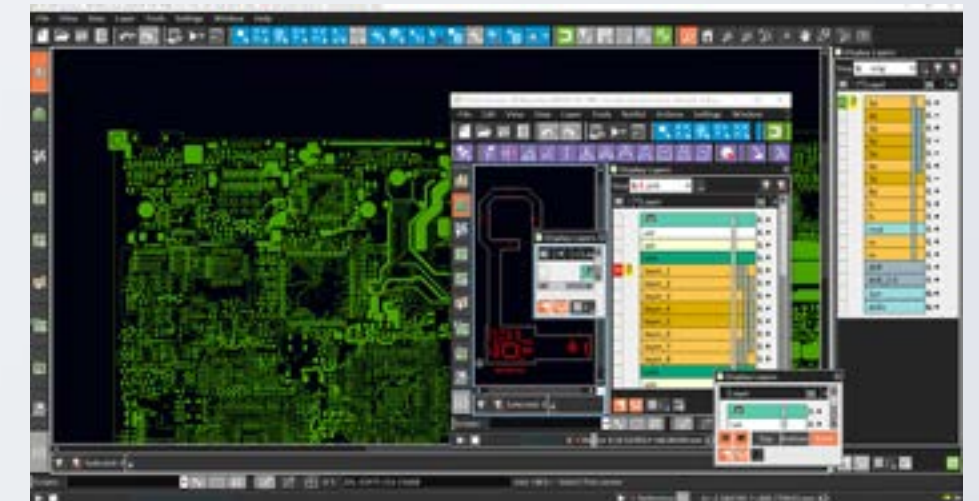
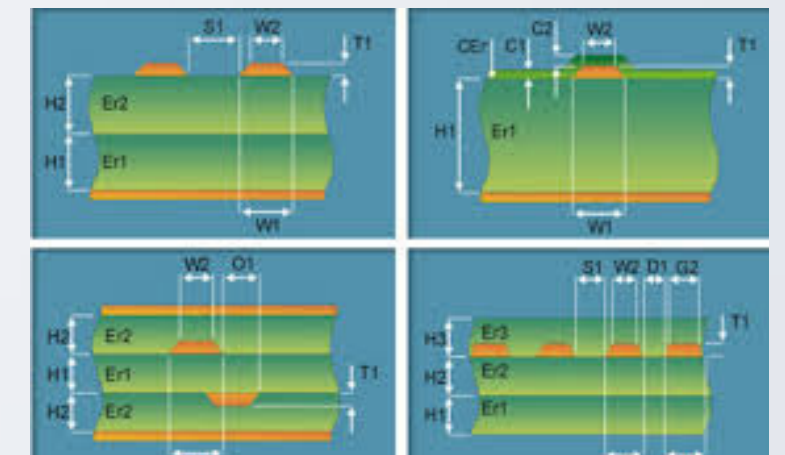
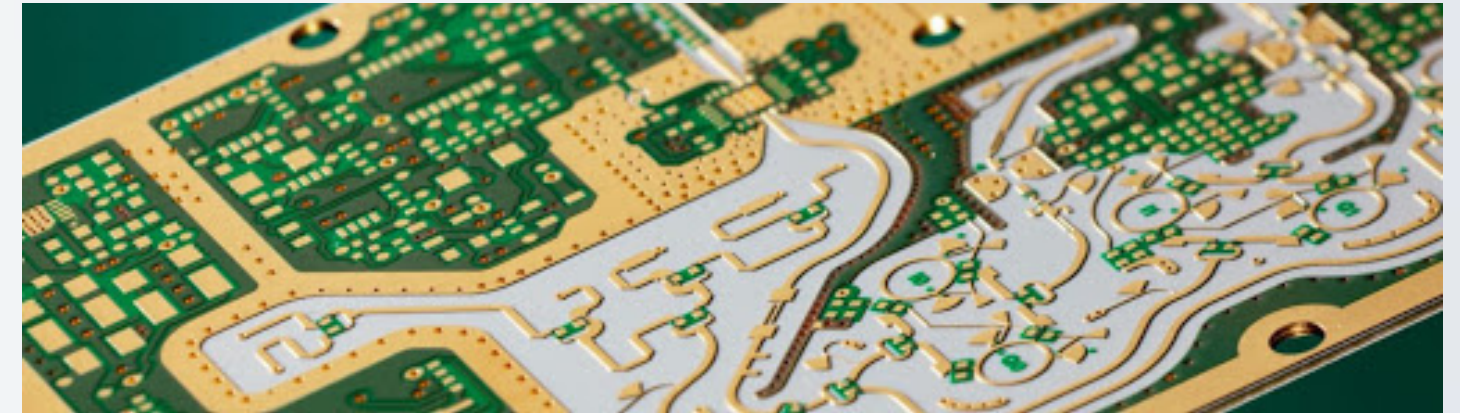
TEFLON PCB PRODUCTION 12/14 W-DAYS

EXTENSIVE STOCK_ISOLA/NELCO/ARLON/ROGERS

CUSTOMIZED STOCK FOR OUR BEST CUSTOMERS

SUPPORTING CUSTOMERS FROM DESIGN TO SHIPPING

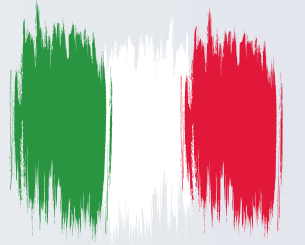
IPC-A-600 CLASS 2 & CLASS 3



ESSETI HQ:



AUTOMATIC VERTICAL LIFT MODULE



ADVANTAGES:

SAVE TIME DURING RAW MATERIAL HANDLING

HELP THE OPERATOR TO EXTRACT THE CORRECT RAW MATERIALS

HELP THE SALES DEPARTMENT TO KNOW IF THERE IS ENOUGH RAW MATERIAL IN STOCK FOR THE NEW PO

ENSURE THE CUSTOMER THE PERFECT TRACEABILITY OF THE RAW MATERIALS

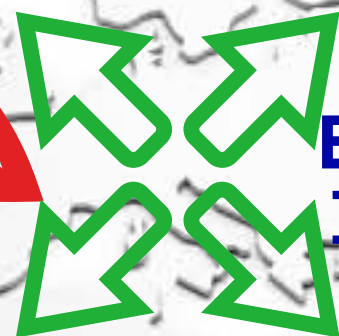




**USA
PARTNER**



Checking Quality



**ESSETI
ITA HQ** 



**FAR EAST
PARTNER**

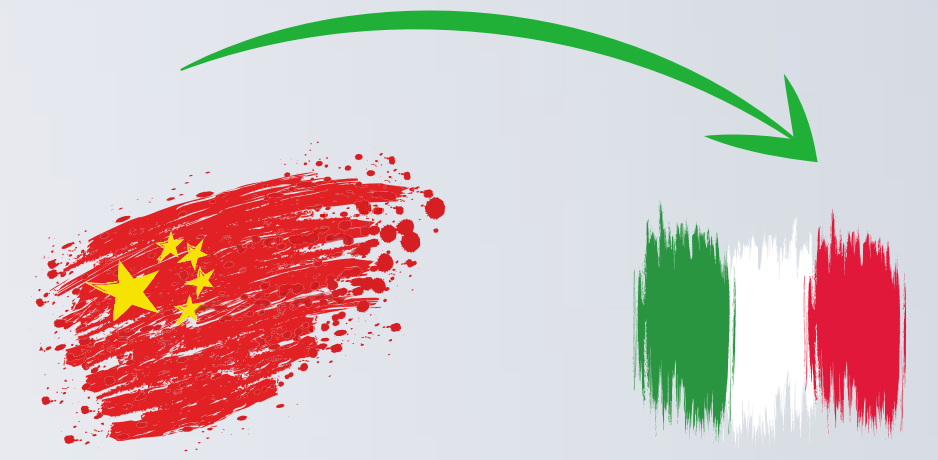
Checking Quality



**THINK GLOBAL
SUPPORT LOCAL**

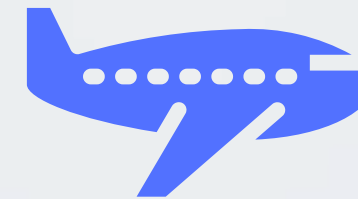
ESSETI HQ:

»» **GUARANTEED IMPORT SERVICE**



ENGINEERING WORKING GERBER PROCESS IN ITALY

LOGISTIC PLANNING (AIR/TRAIN/SHIP)



QUALITY CHECK:

CROSS-SECTION/THERMAL STRESS

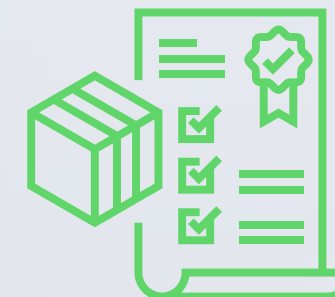
X-RAY/VISUAL INSPECTION/MECHANICAL CHECK

E-TEST/IPC STANDARD VERIFICATION WITH OUR

HIGHLY QUALIFIED IPC INSPECTORS

QUALITY REPORT CREATION:

QA REPORT-COC-FAI CERTIFICATION-



TECHNOLOGIES:

RIGID PCB(SINGLE TO MULTILAYERS)

HDI/MICROVIAS, BLIND/BURIED VIAS TECHNOLOGY

HIGH SPEED DESIGN PCBS

FLEX, RIGID-FLEX, SEMI-FLEX

BACKPLANES

HEAVY COPPER PCB

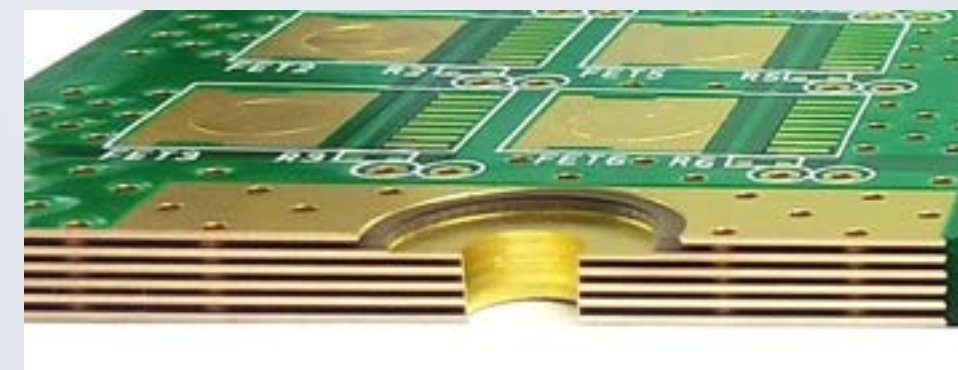
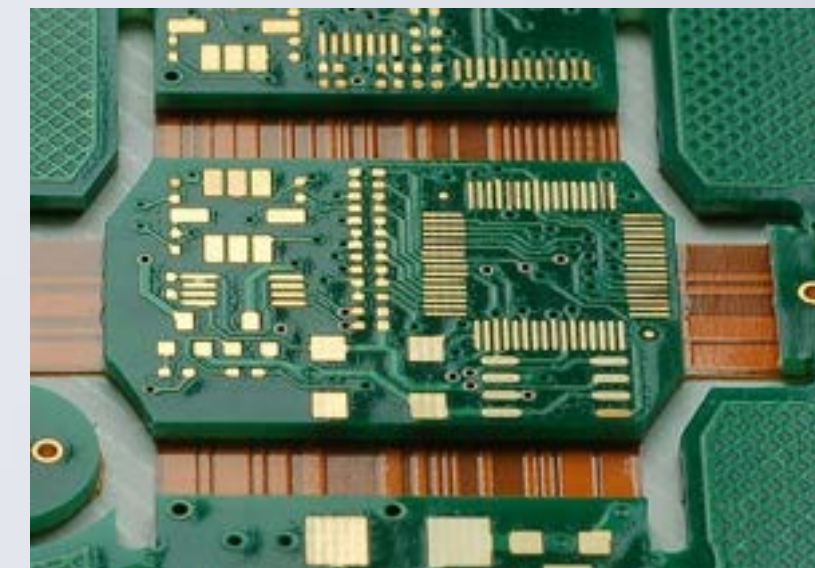
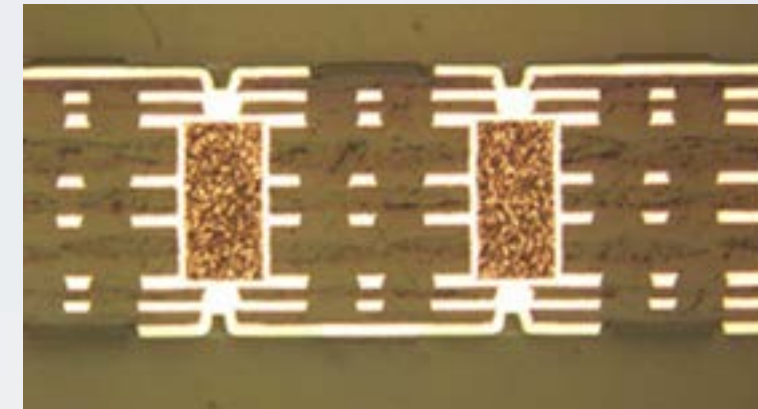
ALUMINIUM (IMS) PCB

COPPER BASE PCB

IMPEDANCE CONTROL

MULTIPLES SURFACE & SELECTIVE FINISHES

MICROSECTION (ON REQUEST)

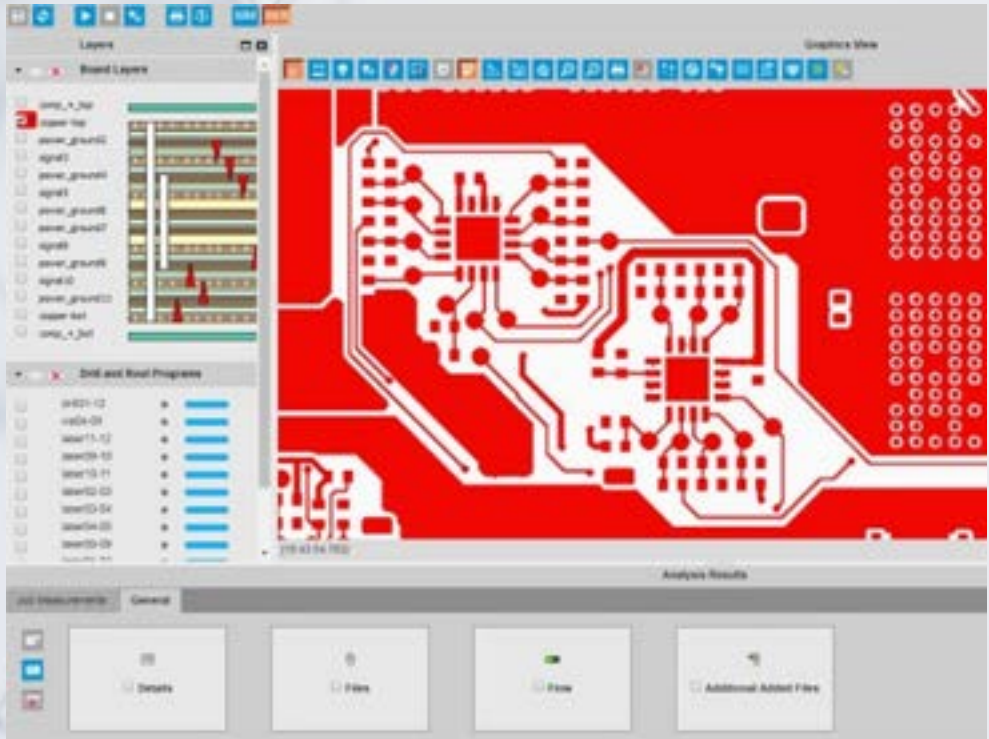


FAST-ACCURATE-COMPETITIVE QUOTATION: ...WITH INSIGHTS PCB SOFTWARE



INSIGHT DFM REPORTS SHOWS:

- PCB SIZE
- MINIMUM HOLE SIZE
- NUMBER OF HOLES
- MINIMUM TRACK AND GAP
- ANNULAR RING CLEARANCES
- MINIMUM CLEARANCES TO COPPER
- HIGHTLIGHTS ANY DFM VIOLATIONS

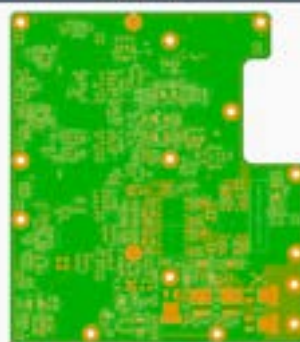




Job (12413_)



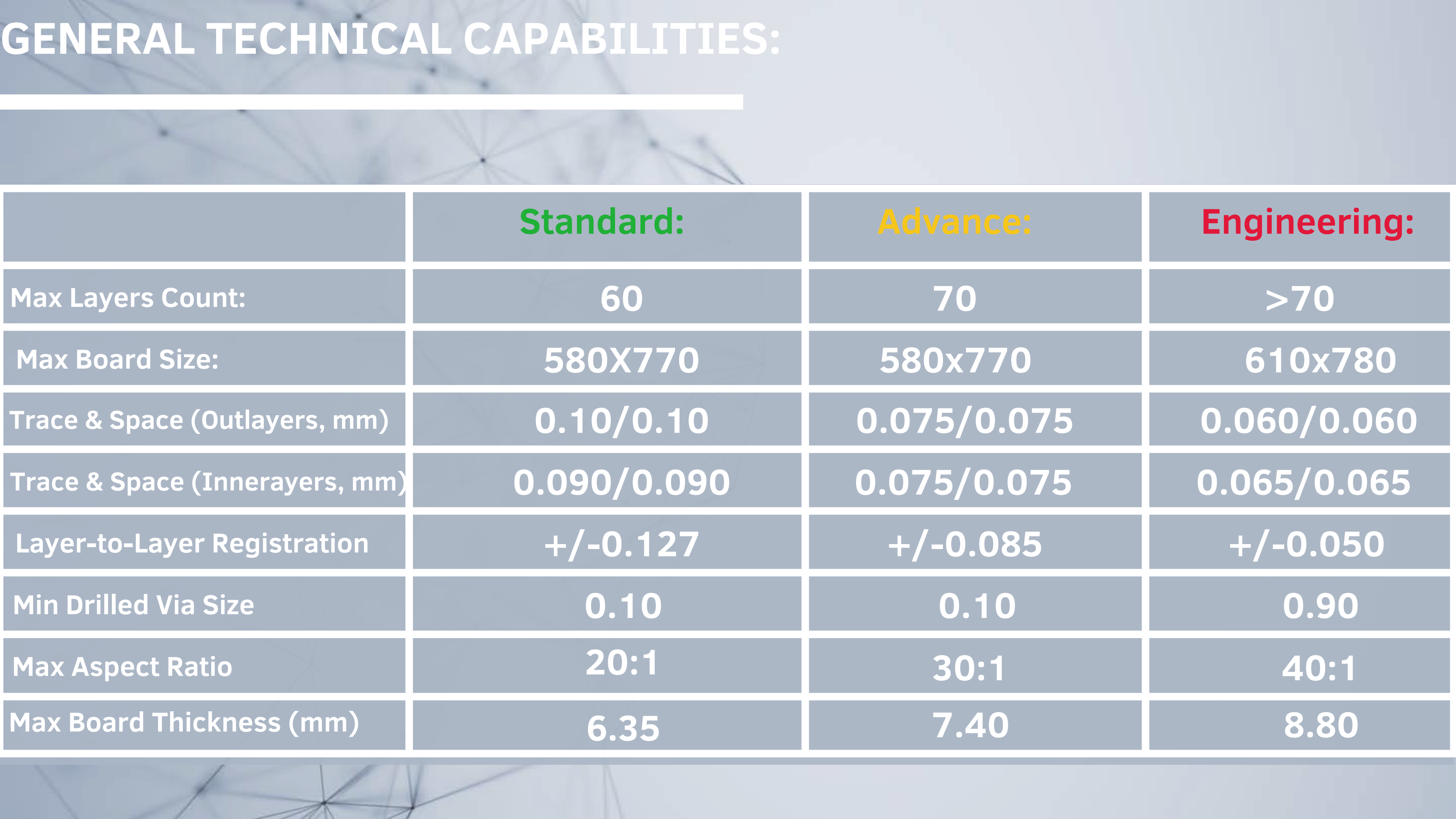
Job Name		Job Type	New Job
Operator	Alberto Zanella	Creation Time	2021-01-13 09:28:00
Part Number		Revision	
Customer Name		Job Class	IPC6012-Class2
Contact Name		Contact Email	

Buildup	Top View	Bottom View
		

Job Info			
Copper Layers	12	Drill Layer	4
Part Size (X,Y)	149.5 x 168 mm	Array Size (X,Y)	0 x 0 mm
PCB Area	22979.73 mm ²	Array Area	0 mm ²
Thickness	2.4 mm	Rout Length	651.679 mm
Top SM Area	18427.679 mm ²	Bottom SM Area	18947.9 mm ²
DL Thickness	35 µm	DL Thickness	35 µm
Soldermask Side	Both	Soldermask Color	Medium-Green
Silkscreen Side	Both	Silkscreen Color	White
Soldermask Type	Undefined	Finish Type	ENIG
Impedance	No	Aspect Ratio (max)	6
Gold Thickness	0 µm	Gold Plating Type	Undefined
Stacked Holes Count	0	Material	FR4 TG170-180
CNC Hole Density	0.094 mm ²	Laser Hole Density	N/A
Plug Holes Volume	960.696 mm ³	Non-Plug Through Holes Volume	6.183 mm ³

Outer Layer Info		
Feature	Top Layer	Bottom Layer
SMD Pads	2035	1653
SMD Min Pitch	500 µm	500 µm
BGA Pads	0	0

With the help of InSight software, we automatically process customers data at the quotation stage and run Design Rule checks. We can then produce detailed DFM reports highlighting the critical areas of the PCB, thus enabling us to provide customers with accurate quotations.



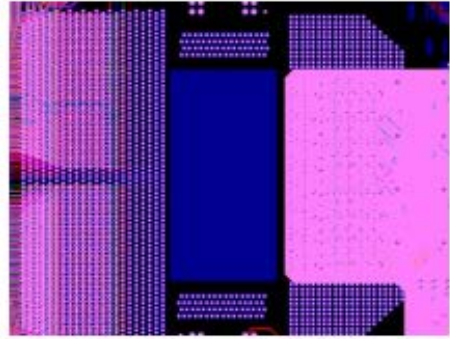
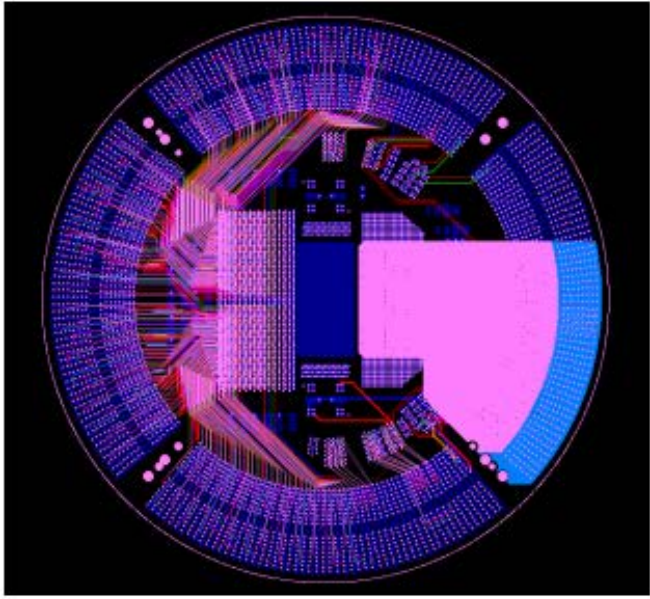
GENERAL TECHNICAL CAPABILITIES:

	Standard:	Advance:	Engineering:
Max Layers Count:	60	70	>70
Max Board Size:	580X770	580x770	610x780
Trace & Space (Outlayers, mm)	0.10/0.10	0.075/0.075	0.060/0.060
Trace & Space (Innerayers, mm)	0.090/0.090	0.075/0.075	0.065/0.065
Layer-to-Layer Registration	+/-0.127	+/-0.085	+/-0.050
Min Drilled Via Size	0.10	0.10	0.90
Max Aspect Ratio	20:1	30:1	40:1
Max Board Thickness (mm)	6.35	7.40	8.80

GENERAL TECHNICAL CAPABILITIES:

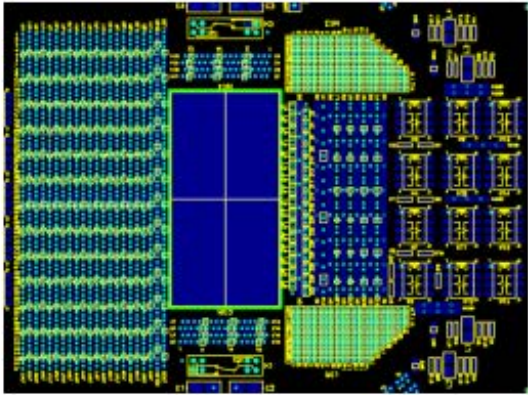
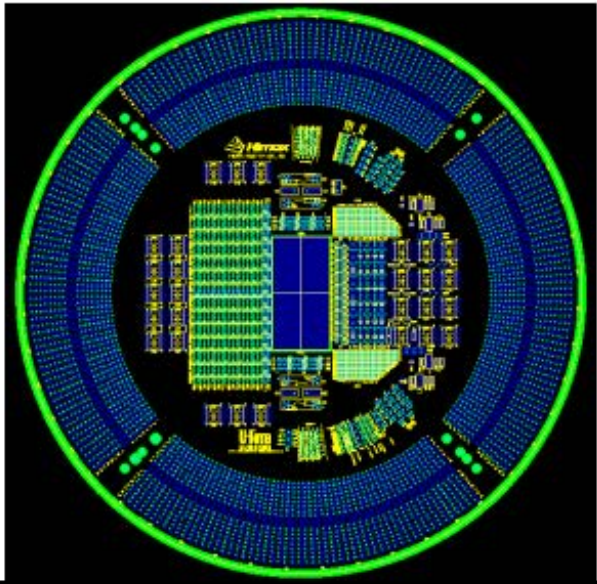
	Standard:	Advance:	Engineering:
Impedance Control (Outer)	+/-10%	+/-8%	+/-7%
Impedance Control (Inner)	+/-10%	+/-5%	+/-4%
Tolerance - Plated Hole Size	+/-0.05	+/- 0.04	+/- 0.04
Base Material	ISOLA - ARLON/ROGERS - NELCO - SHENGYI - ITEQ - TACONIC- AISMALIBAR-DENKA-BERGQUIST-VENTEC		





Min hole SIZE:
0.4Ø
Hole total:
4241 EA

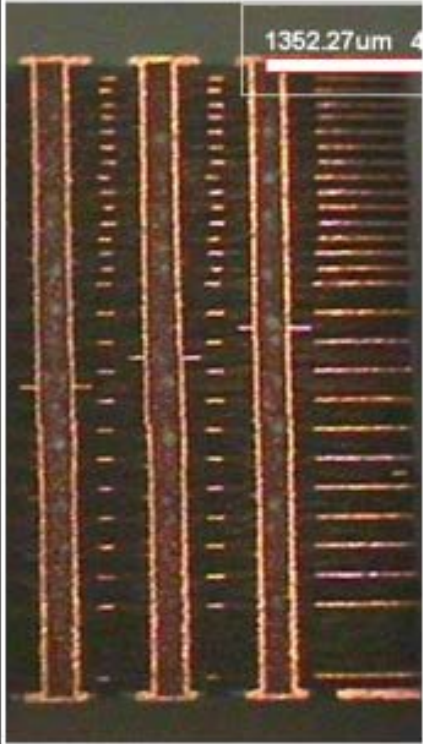
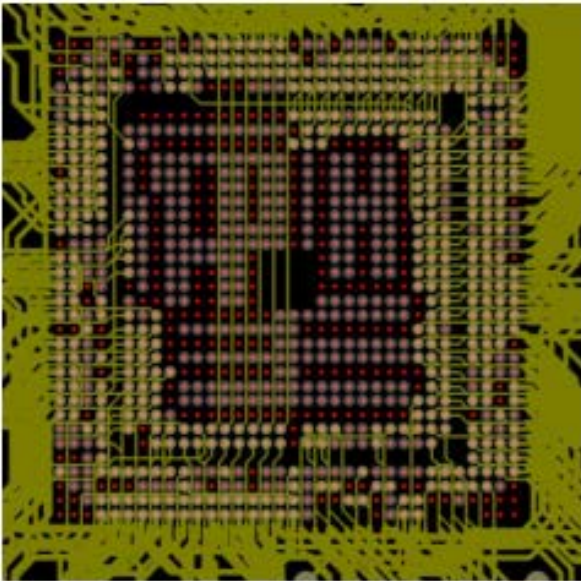
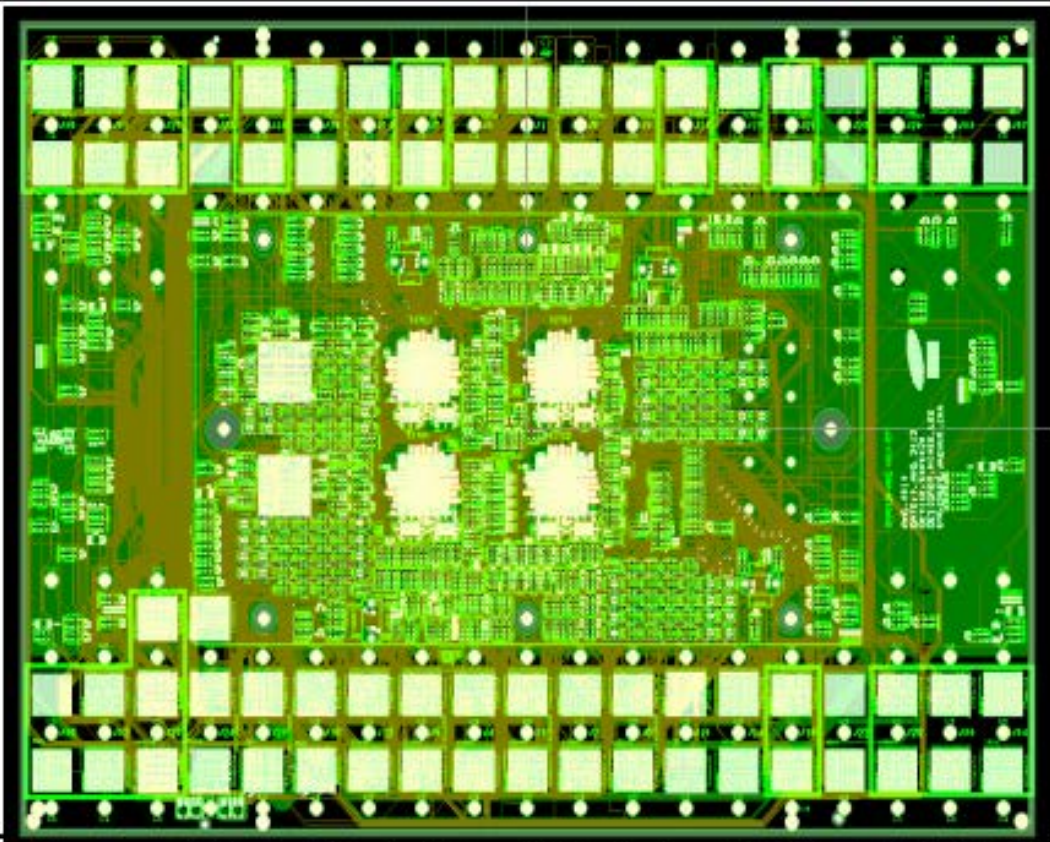
Thickness:6.35T Layers:20L Material:FR-5 Size:279.4Ø



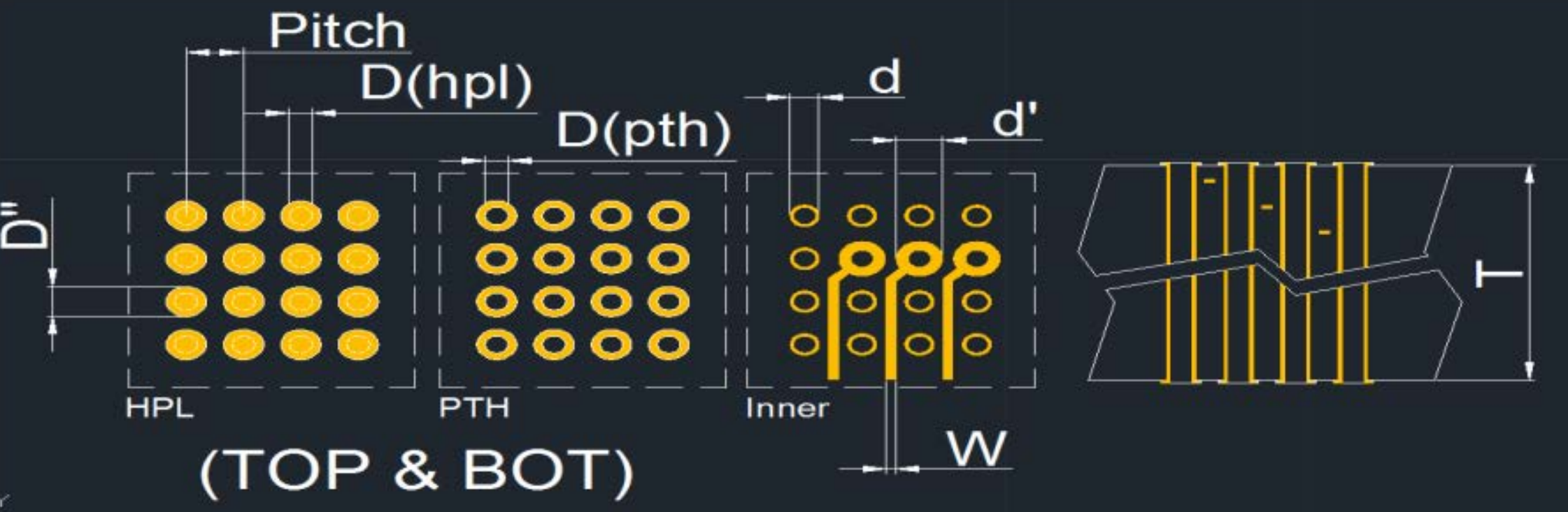
Min hole SIZE:
0.45Ø
Hole
total: 6356 EA

TOP CS / HP

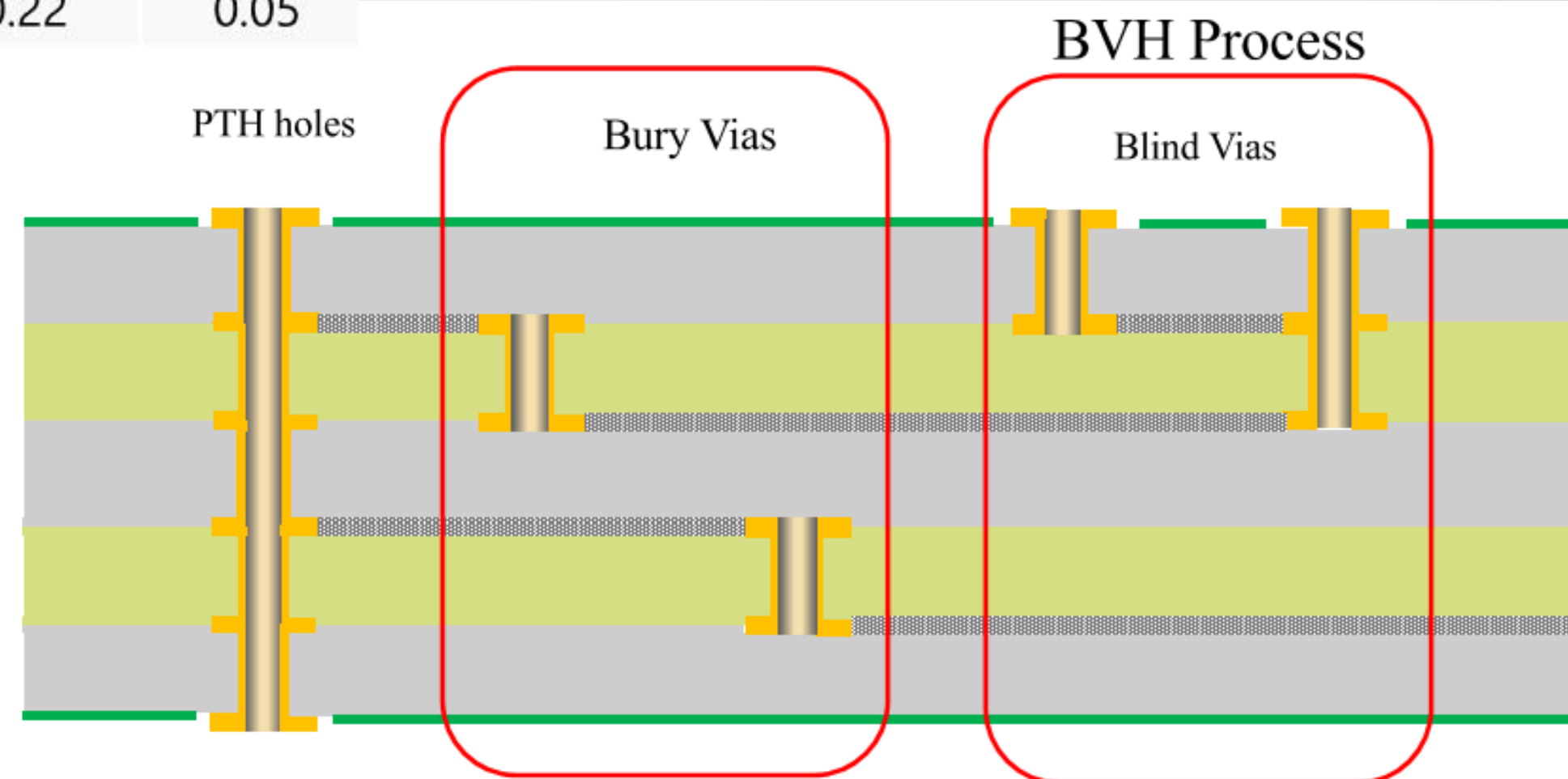
Thickness:6.35T Layers:28L Material:FR-5 Size:300Ø

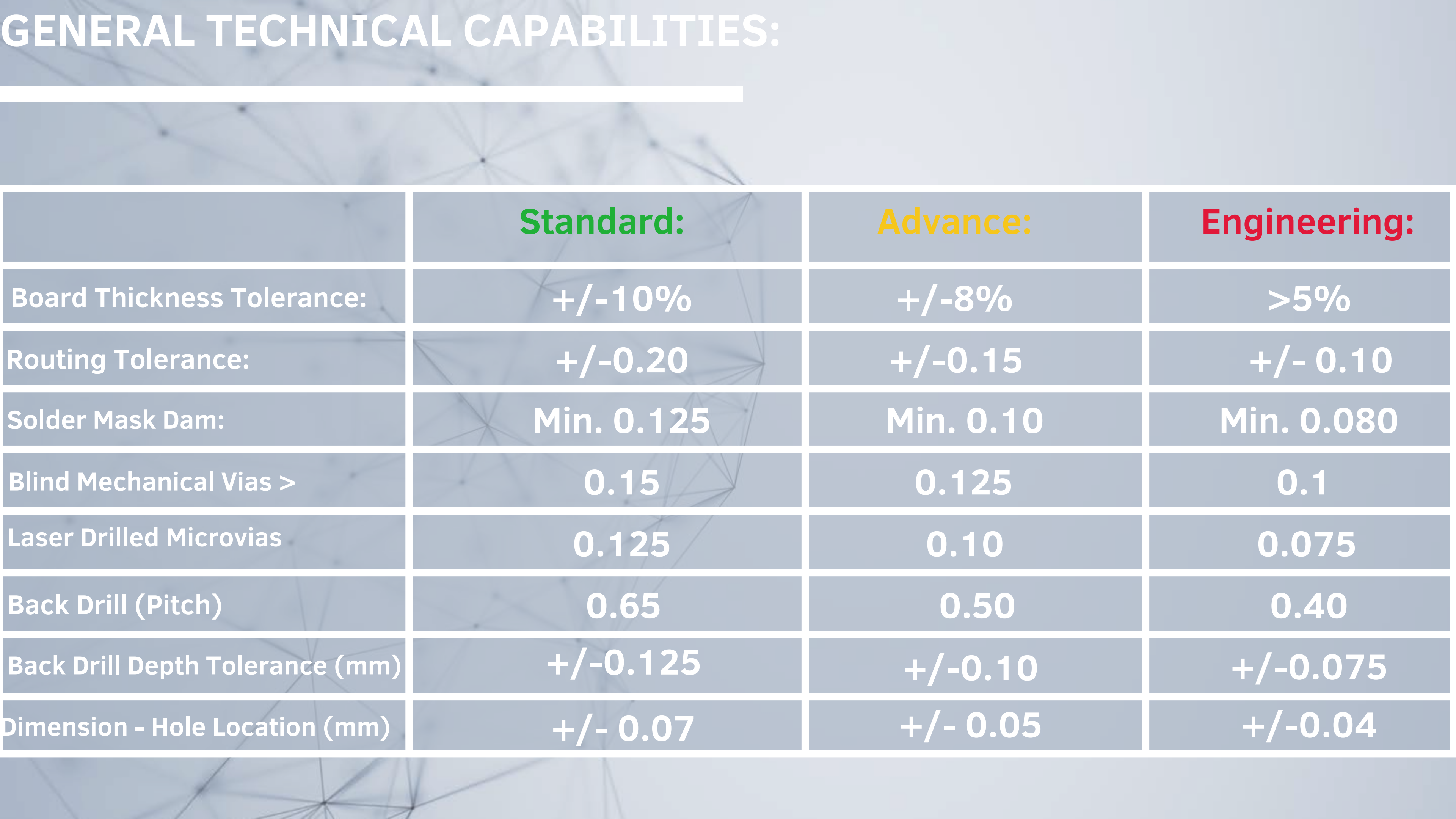


Spec	FR4 0.4 Pitch 4 Para (988 Holes / 1~27L drill / 28~32L drill / 1~32L drill
Size	403 mm x 508 mm
Thickness	4.8T
Layers	32L



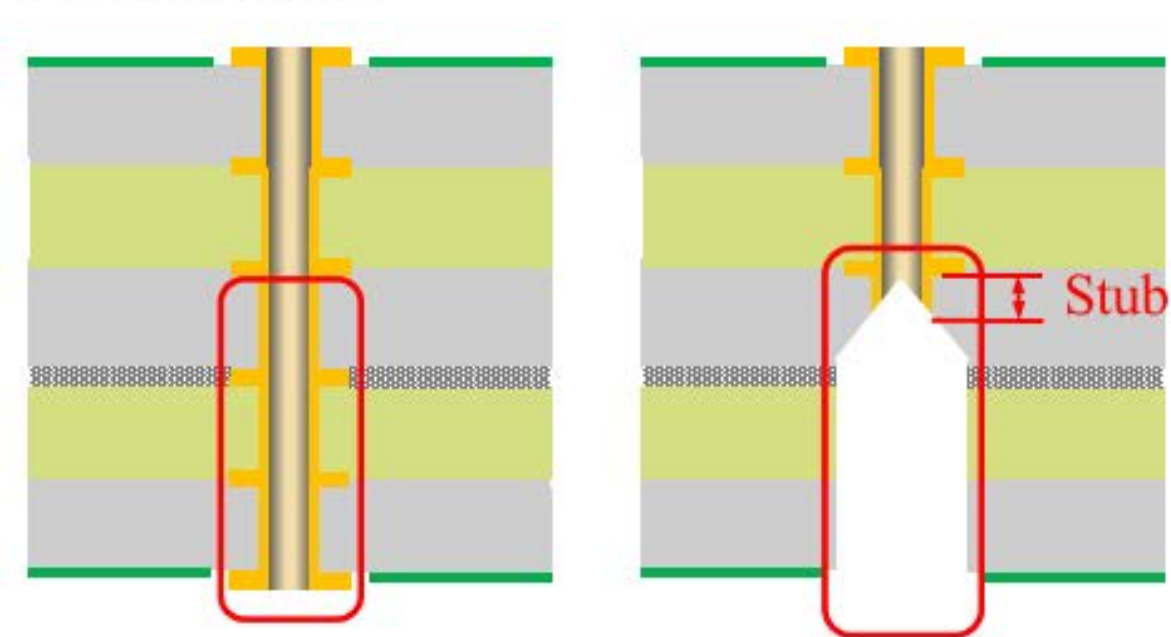
Pitch	T(Max)	D'' (Max)	D(HPL)	D(PTH)	d	d'	W
0.5	6.3	0.34	0.25	0.25	0.43	0.42	0.07
0.4	6.3	0.24	0.175	0.175	0.34	0.32	0.06
0.35	5.0	0.19	0.15	0.15	0.295	0.27	0.055
0.3	1.6	0.14	0.13	0.13	0.25	0.22	0.05



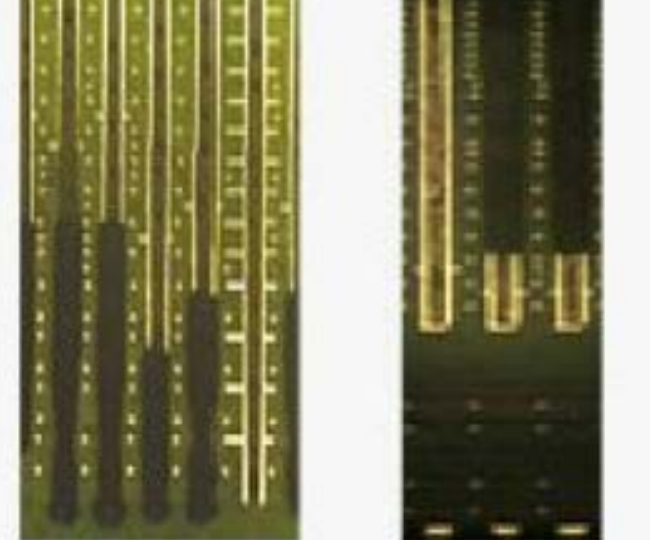


GENERAL TECHNICAL CAPABILITIES:

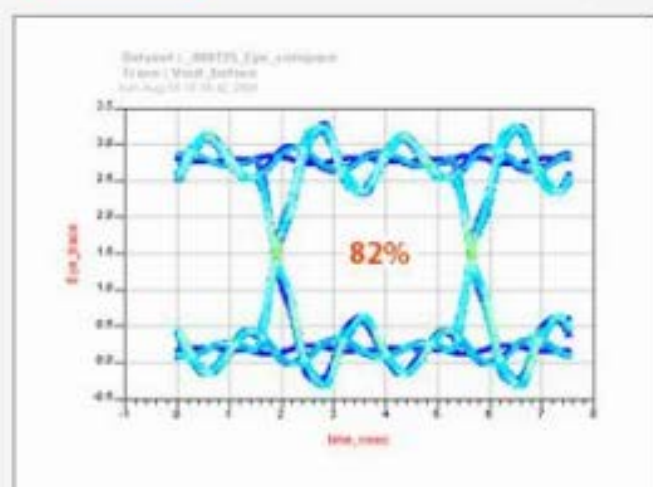
	Standard:	Advance:	Engineering:
Board Thickness Tolerance:	+/-10%	+/-8%	>5%
Routing Tolerance:	+/-0.20	+/-0.15	+/- 0.10
Solder Mask Dam:	Min. 0.125	Min. 0.10	Min. 0.080
Blind Mechanical Vias >	0.15	0.125	0.1
Laser Drilled Microvias	0.125	0.10	0.075
Back Drill (Pitch)	0.65	0.50	0.40
Back Drill Depth Tolerance (mm)	+/-0.125	+/-0.10	+/-0.075
Dimension - Hole Location (mm)	+/- 0.07	+/- 0.05	+/-0.04



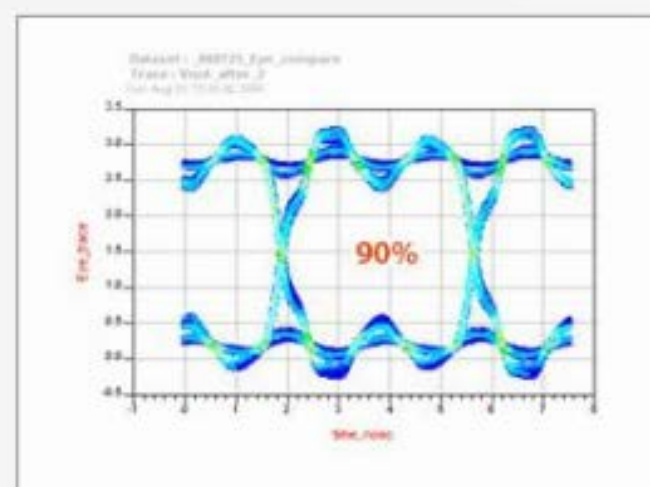
Stub



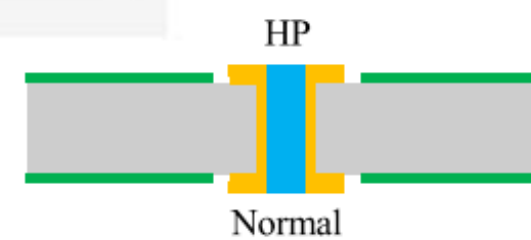
0.5 Pitch Board 0.4 Pitch Board



< Normal >



< Back Drilling >



Normal



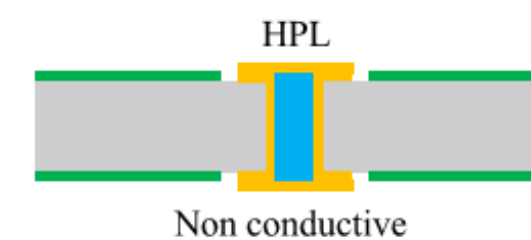
PSR on top side



PSR on bottom side



PSR on both side



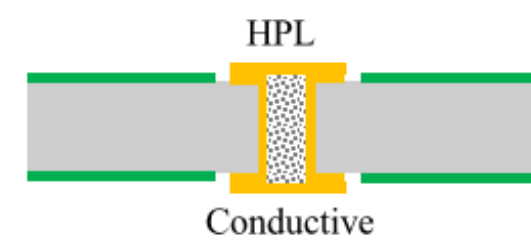
Non conductive



PSR on top side



PSR on bottom side



Conductive

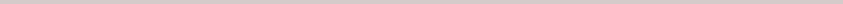


PSR on top side

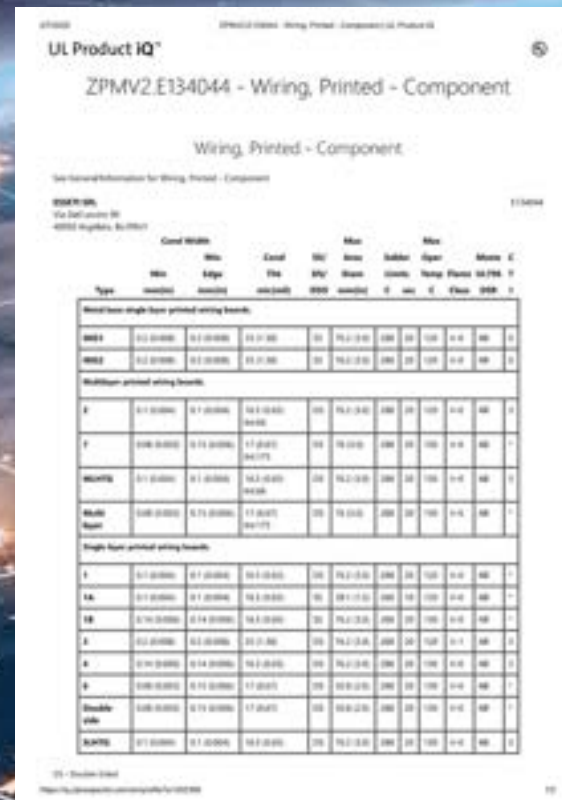


PSR on bottom side





FULL LABORATORY FACILITIES AND REPORTING IN ITALY



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**„TALENT WINS GAMES, BUT TEAMWORK AND
INTELLIGENCE WINS CHAMPIONSHIPS.“**

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VISIT ESSETI HQ

CLICK!

